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TAIYO YUDEN 2013

CHIP BEAD INDUCTORS FOR POWER LINES (FB SERIES M TYPE)



PARTS NUMB	ER				
F B Δ	MJ32 23 4	0 11 0 0	0 0 - 6 (7	- T (Δ) 7 (8) (9)	$\Delta=$ Blank space
) Series name				⑤Material	
Code	Serie	s name		Code	Material
FB	Ferrit	e bead	_	HS	Defende innedense som
			-	HM	Refer to impedance curves for material differences
Shape			_	HL	for material differences
Code	Sł	ape			
М	Rectan	gular chip	_	6Nominal imped	ance
3)Characteristics	s		_	Code (example)	Nominal impedance [Ω]
Code	Charac	teristics		330	33
J	Sta	ndard	-	111	110
Н	High Impe	dance type	-	132	1300
Dimensions (L	×W)			⑦Impedance tol	erance
Code	Type(inch)	Dimensions		Code	Impedance tolerance
oode		(L×W)[mm]			±25%
1608	1608(0603)	1.6 × 0.8	_	N	±30%
2125	2125(0805)	2.0 × 1.25			
2012	2012(0805)	2.0 / 1.20	_	8 Packaging	
2016	2016(0806)	2.0 × 1.6	_	Code	Packaging
3216	3216(1206)	3.2 × 1.6	_	Т	Taping
3225	3225(1210)	3.2 × 2.5	-		
4516	4516(1806)	4.5 × 1.6	-	<pre>⑨Internal code</pre>	
4525	4525(1810)	4.5 × 2.5	-	Code	Internal code
4532	4532(1812)	4.5 × 3.2	-	Δ	Standard
			-		

STANDARD EXTERNAL DIMENSIONS / STANDARD QUANTITY





Туре	A	В	С
FB MJ1608	1.0	1.0	1.0
FB MJ2125	1.4	1.2	1.65
FB MJ3216	1.4	2.2	2.0
FB MJ4516	1.75	3.5	2.0
FB MH1608	1.0	1.0	1.0
FB MH2012	1.4	1.2	1.65
FB MH2016	1.4	1.2	2.0
FB MH3216	1.4	2.2	2.0
FB MH4516	1.75	3.5	2.0
FB MH3225	1.4	2.2	2.9
FB MH4525	1.75	3.5	2.9
FB MH4532	1.75	3.5	3.7

ntity [pcs]	Standard qua		т	w	1	Type
Embossed tape	Paper tape	e	1	VV	L	туре
	4000	0.3±0.2	0.8±0.2	0.8±0.2	1.6±0.2	FB MJ1608
-	4000	(0.012±0.008)	(0.031 ± 0.008)	(0.031 ± 0.008)	(0.063±0.008)	(0603)
_	4000	0.5±0.3	0.85±0.2	1.25±0.2	2.0±0.2	FB MJ2125
	4000	(0.020±0.012)	(0.033 ± 0.008)	(0.049 ± 0.008)	(0.079±0.008)	(0805)
2000	_	0.5±0.3	1.1±0.2	1.6±0.2	3.2±0.3	FB MJ3216
2000	—	(0.020±0.012)	(0.043 ± 0.008)	(0.063 ± 0.008)	(0.126±0.012)	(1206)
2000		0.5±0.3	1.1±0.2	1.6±0.2	4.5±0.3	FB MJ4516
2000	—	(0.020 ± 0.012)	(0.043 ± 0.008)	(0.063 ± 0.008)	(0.177±0.012)	(1806)
	4000	0.3±0.15	0.8±0.1	0.8±0.1	1.6±0.1	FB MH1608
-	4000	(0.012±0.006)	(0.031 ± 0.004)	(0.031 ± 0.004)	(0.063±0.004)	(0603)
	4000	0.5±0.3	0.85±0.2	1.25±0.2	2.0±0.2	FB MH2012
-	4000	(0.020 ± 0.012)	(0.033 ± 0.008)	(0.049 ± 0.008)	(0.079±0.008)	(0805)
2000	_	0.5±0.3	1.6±0.2	1.6±0.2	2.0±0.2	FB MH2016
2000	—	(0.020 ± 0.012)	(0.063 ± 0.008)	(0.063 ± 0.008)	(0.079±0.008)	(0806)
2000		0.5±0.3	1.6±0.2	1.6±0.2	3.2±0.3	FB MH3216
2000	-	(0.020±0.012)	(0.063 ± 0.008)	(0.063 ± 0.008)	(0.126±0.012)	(1206)
1000		0.5±0.3	2.5±0.3	2.5±0.3	3.2±0.3	FB MH3225
1000	-	(0.020±0.012)	(0.098±0.012)	(0.098±0.012)	(0.126±0.012)	(1210)
2000		0.5±0.3	1.6±0.2	1.6±0.2	4.5±0.3	FB MH4516
2000		(0.020 ± 0.012)	(0.063 ± 0.008)	(0.063 ± 0.008)	(0.177±0.012)	(1806)
1000		0.9±0.6	2.5±0.3	2.5±0.3	4.5±0.4	FB MH4525
1000	—	(0.035 ± 0.024)	(0.098±0.012)	(0.098±0.012)	(0.177±0.016)	(1810)
2000	_	0.9±0.6	3.2±0.3	3.2±0.3	4.5±0.4	FB MH4532
2000	-	(0.035 ± 0.024)	(0.126±0.012)	(0.126±0.012)	(0.177±0.016)	(1812)

Standard type FB MJ1608

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MJ1608HS280NT	RoHS	28	±30%	100	0.007	4.0	0.8 ±0.2
FB MJ1608HM230NT	RoHS	23	±30%	100	0.007	4.0	0.8 ±0.2

FB MJ2125

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MJ2125HS420-T	RoHS	42	±25%	100	0.008	4.0	0.85 ± 0.2
FB MJ2125HS250NT	RoHS	25	$\pm 30\%$	100	0.004	6.0	0.85 ± 0.2
FB MJ2125HM330-T	RoHS	33	±25%	100	0.008	4.0	0.85 ± 0.2
FB MJ2125HM210NT	RoHS	21	±30%	100	0.004	6.0	0.85 ±0.2
FB MJ2125HL8R0NT	RoHS	8	±30%	100	0.008	4.0	0.85 ± 0.2

FB MJ3216

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MJ3216HS800-T	RoHS	80	±25%	100	0.010	4.0	1.1 ±0.2
FB MJ3216HS480NT	RoHS	48	$\pm 30\%$	100	0.005	6.0	1.1 ±0.2
FB MJ3216HM600-T	RoHS	60	±25%	100	0.010	4.0	1.1 ±0.2
FB MJ3216HM380NT	RoHS	38	$\pm 30\%$	100	0.005	6.0	1.1 ±0.2
FB MJ3216HL160NT	RoHS	16	$\pm 30\%$	100	0.012	4.0	1.1 ±0.2

FB MJ4516

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MJ4516HS111-T	RoHS	110	±25%	100	0.014	4.0	1.1 ±0.2
FB MJ4516HS720NT	RoHS	72	$\pm 30\%$	100	0.007	6.0	1.1 ± 0.2
FB MJ4516HM900-T	RoHS	90	±25%	100	0.014	4.0	1.1 ± 0.2
FB MJ4516HM560NT	RoHS	56	$\pm 30\%$	100	0.007	6.0	1.1 ± 0.2
FB MJ4516HL230NT	RoHS	23	$\pm 30\%$	100	0.014	3.5	1.1 ± 0.2

High impedance type FB MH1608

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MH1608HM470-T	RoHS	47	±25%	100	0.020	3.5	0.8 ±0.1
FB MH1608HM600-T	RoHS	60	±25%	100	0.025	3.0	0.8 ±0.1
FB MH1608HM101-T	RoHS	100	±25%	100	0.035	2.0	0.8 ±0.1
FB MH1608HM151-T	RoHS	150	±25%	100	0.050	2.0	0.8 ±0.1
FB MH1608HM221-T	RoHS	220	±25%	100	0.070	1.5	0.8 ±0.1
FB MH1608HM331-T	RoHS	330	±25%	100	0.130	0.9	0.8 ±0.1
FB MH1608HM471-T	RoHS	470	±25%	100	0.150	0.7	0.8 ±0.1
FB MH1608HM601-T	RoHS	600	±25%	100	0.170	0.7	0.8 ±0.1
FB MH1608HM102-T	RoHS	1000	±25%	100	0.350	0.5	0.8 ±0.1
FB MH1608HL300-T	RoHS	30	±25%	100	0.028	2.5	0.8 ±0.1
FB MH1608HL600-T	RoHS	60	±25%	100	0.045	1.8	0.8 ±0.1
FB MH1608HL121-T	RoHS	120	±25%	100	0.130	0.9	0.8 ±0.1
FB MH1608HL221-T	RoHS	220	±25%	100	0.170	0.7	0.8 ±0.1
FB MH1608HL331-T	RoHS	330	±25%	100	0.210	0.6	0.8 ±0.1
FB MH1608HL471-T	RoHS	470	±25%	100	0.350	0.5	0.8 ±0.1
FB MH1608HL601-T	RoHS	600	±25%	100	0.450	0.4	0.8 ±0.1

FB MH2012

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MH2012HM800-T	RoHS	80	±25%	100	0.025	2.7	0.85 ± 0.2
FB MH2012HM121-T	RoHS	120	$\pm 25\%$	100	0.032	2.5	0.85 ± 0.2
FB MH2012HM221-T	RoHS	220	±25%	100	0.060	2.0	0.85 ± 0.2
FB MH2012HM331-T	RoHS	330	±25%	100	0.080	1.8	0.85 ± 0.2

FB MH2016

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MH2016HM121NT	RoHS	120	±30%	100	0.015	4.5	1.6 ±0.2
FB MH2016HM251NT	RoHS	250	$\pm 30\%$	100	0.050	2.0	1.6 ±0.2

FB MH3216

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MH3216HM221NT	RoHS	220	±30%	100	0.020	4.0	1.6 ±0.2
FB MH3216HM501NT	RoHS	500	$\pm 30\%$	100	0.070	2.0	1.6 ±0.2

FB MH3225

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MH3225HM601NT	RoHS	600	±30%	100	0.042	3.0	2.5 ±0.3
FB MH3225HM102NT	RoHS	1000	±30%	100	0.100	2.0	2.5 ± 0.3
FB MH3225HM202NT	RoHS	2000	±30%	100	0.130	1.2	2.5 ± 0.3

FB MH4516 Measuring frequency [MHz] DC Resistance [Ω](max.) Rated current [A] (max.) Thickness [mm] Nominal impedance (Ω) Parts number EHS Impedance tolerance FB MH4516HM851NT RoHS ±30% 100 0.100 1.5 1.6 ±0.2 850

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A](max.)	Thickness [mm]
FB MH4525HM102NT	RoHS	1000	±30%	100	0.060	3.0	2.5 ±0.3
FB MH4525HM162NT	RoHS	1600	±30%	100	0.130	2.0	2.5 ±0.3

FB MH4532

- I B IIII I I III							
Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A](max.)	Thickness [mm]
FB MH4532HM681-T	RoHS	680	±25%	100	0.028	4.0	3.2 ±0.3
FB MH4532HM132-T	RoHS	1300	±25%	100	0.060	3.0	3.2 ±0.3
FB MH4532HM202-T	RoHS	2000	±25%	100	0.130	1.3	3.2 ±0.3

High current type

Parts number	EHS	Nominal impedance (Ω)	Impedance tolerance	Measuring frequency [MHz]	DC Resistance [Ω](max.)	Rated current [A] (max.)	Thickness [mm]
FB MJ1608HS220NTR	RoHS	22	±30%	100	0.004	7.5	0.8 ±0.2
FB MJ1608HS280NTR	RoHS	28	±30%	100	0.006	6.0	0.8 ±0.2
FB MJ1608HM180NTR	RoHS	18	±30%	100	0.004	7.5	0.8 ±0.2
FB MJ1608HM230NTR	RoHS	23	±30%	100	0.006	6.0	0.8 ±0.2

ELECTRICAL CHARACTERISTICS





This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (http://www.ty-top.com/). NOISE SUPPRESSION COMPONENTS / FERRITE BEAD INDUCTORS

ELECTRICAL CHARACTERISTICS

Standard type



ELECTRICAL CHARACTERISTICS







NOISE SUPPRESSION COMPONENTS / FERRITE BEAD INDUCTORS

CHIP BEAD INDUCTORS FOR POWER LINES (FB SERIES M TYPE)

PACKAGING

①Minimum Quantity		
Туре	Standard Q	uantity[pcs]
	Paper Tape	Embossed Tape
1608(0603)	4000	-
2125(0805)	4000	-
2012(0805)	4000	—
2016(0806)	-	2000
3216(1206)	-	2000
4516(1806)	-	2000
3225(1210)	-	1000
4525(1810)	-	1000
4532(1812)	-	2000

②Tape Material

Card board carrier tape







Turne	Chip	Cavity	Insertion Pitch	Tape Thickness
Туре	A	В	F	Т
FBMJ1608 FBMH1608 (0603)	1.0 ± 0.2 (0.039±0.008)	1.8±0.2 (0.071±0.008)	4.0±0.2 (0.157±0.008)	1.1max (0.043max)
FBMJ2125 FBMH2012 (0805)	1.5 ± 0.2 (0.059 ± 0.008)	2.3±0.2 (0.091±0.008)	4.0±0.2 (0.157±0.008)	1.1max (0.043max)

Unit : mm(inch)

Embossed tape (0.315 inches wide)



Turne	Chip Cavity		Insertion Pitch	Tape Thickness	
Туре	Α	В	F	К	Т
FBMH2016	1.8±0.2	2.2±0.2	4.0±0.2	2.6max	0.6max
(0806)	(0.071 ± 0.008)	(0.087±0.008)	(0.157 ± 0.008)	(0.102max)	(0.024max)
FBMJ3216	1.9±0.2	3.5±0.2	4.0±0.2	1.5max	0.3max
(1206)	(0.075 ± 0.008)	(0.138 ± 0.008)	(0.157 ± 0.008)	(0.059max)	(0.012max)
FBMH3216	1.9±0.2	3.5±0.2	4.0±0.2	2.6max	0.6max
(1206)	(0.075 ± 0.008)	(0.138 ± 0.008)	(0.157 ± 0.008)	(0.102max)	(0.024max)
FBMH3225	2.8±0.2	3.5±0.2	4.0±0.2	4.0max	0.6max
(1210)	(0.110±0.008)	(0.138 ± 0.008)	(0.157 ± 0.008)	(0.157max)	(0.024max)

Unit : mm(inch)

Embossed tape (0.472 inches wide)



T	Chip Cavity		Insertion Pitch	Tape Thickness	
Туре	A	В	F	К	Т
FBMJ4516	1.9±0.2	4.9±0.2	4.0±0.2	1.5max	0.3max
(1806)	(0.075±0.008)	(0.193±0.008)	(0.157±0.008)	(0.059max)	(0.012max)
FBMH4516	1.9 ± 0.2	4.9±0.2	4.0±0.2	2.6max	0.6max
(1806)	(0.075 ± 0.008)	(0.193±0.008)	(0.157±0.008)	(0.102max)	(0.024max)
FBMH4525	2.9±0.2	4.9±0.2	4.0±0.2	4.0max	0.6max
(1810)	(0.114±0.008)	(0.193±0.008)	(0.157±0.008)	(0.157max)	(0.024max)
FBMH4532	3.6 ± 0.2	4.9±0.2	8.0±0.2	4.0max	0.6max
(1812)	(0.142 \pm 0.008)	(0.193±0.008)	(0.315±0.008)	(0.157max)	(0.024max)

Unit : mm(inch)



4Leader and Blank portion



Direction of tape feed

Insertion leader is 400 mm or more (including 20 empty cavities) Empty cavities at end of reel: 40 holes or more

⑤Reel size



6 Top tape strength



Base tape

The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.

CHIP BEAD INDUCTORS FOR POWER LINE (FB SERIES M TYPE)

RELIABILITY DATA

1. Operating Temperature Range				
Specified Value	$-40^{\circ}C \sim +125^{\circ}C$ Including self-generated heat			

2. Storage Tempera	2. Storage Temperature Range			
Specified Value	-40°C~+85°C			
Test Methods and Remarks	*Note: 0 to +40°C in taped packaging			

3. Impedance		
Specified Value	Within the specified tolera	nce
Test Methods and Remarks	Measuring equipment Measuring frequency	: Impedance analyzer (HP4291A) or its equivalent : 100±1 MHz

4. DC Resistance	
Specified Value	Within the specified range
Test Methods and	Four-terminal method
Remarks	Measuring equipment : Milliohm High-Tester 3226 (Hioki Denki) or its equivalent

5. Rated Current				
Specified Value	Within the specified range			

6. Vibration			
Specified Value	Appearance	: No significant abnormality	
	Impedance change	: Within $\pm 30\%$ of the initial value	
	According to JIS C 0040.		
	Vibration type	: A	
Test Methods and	Time	: 2 hrs each in X,Y, and Z directions Total: 6 hrs	
Remarks	Frequency range	: 10 to 55 to 10Hz (/min.)	
	Amplitude	: 1.5 mm (shall not exceed acceleration 196m/s²)	
	Mounting method	: Soldering onto PC board	

7. Solderability			
Specified Value	90% or more of immersed surface of terminal electrode shall be covered with fresh solder.		
	Solder temperature	: 230±5°C	
Test Methods and	Immersion time	: 4±1 sec.	
Remarks	Preconditioning	: Immersion into flux.	
	Immersion and Removal speed	: 25mm/sec.	

Specified Value	Appearance : No sign	ficant abnormality
Specified value	Impedance change : Within :	±30% of the initial value
	Preheating	: 150°C for 3 min.
	Resistance to Soldering Heat	: 260±5°C
Test Methods and	Duration	: 10±0.5 sec.
Remarks	Preconditioning	: Immersion into flux.
	Immersion and Removal speed	: 25mm/sec.
	Recovery	: 2 to 3 hrs of recovery under the standard condition after the test.

9. Thermal Shock				
Specified Value	Appearar Impedan		nt abnormality ´—10% of the initial value	
		g to JIS C 0025. ns for 1 cycle		_
	Sep	Temperature (°C)	Duration (min.)	
	1	−40±3°C	30 ± 3	
est Methods and	2	Room Temperature	Within 3	1
narks	3	85±2°C	30±3	1
emarks	4	Room Temperature	Within 3	1
	Number Mounting Recover	; method : Soldering or		- d condition after the removal from test chamber

10. Resistance to H	10. Resistance to Humidity (steady state)			
Specified Value	Appearances Impedance change	: No significant abnormality : Within $\pm 30\%$ of the initial value		
Test Methods and Remarks	Temperature Humidit Duration Mounting method Recovery	: 40±2°C : 90 to 95% RH : 500+24/-0 : Soldering onto PC board : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.		

11. Loading under Damp Heat		
Specified Value	Appearance Impedance change	No significant abnormality Within $\pm 30\%$ of the initial value
Test Methods and Remarks	Temperature Humidity Applied current Duration Mounting method Recovery	: 40±2°C : 90 to 95%RH : Rated current : 500+24/-0 hrs : Soldering oto PC board : 2 to 3hrs of recovery under the standard condition after the removal from test chamber.

12. High Temperatu	12. High Temperature Loading Test			
Specified Value	Appearance Impedance change	: No significant abnormality : Within $\pm 30\%$ of the initial value		
Test Methods and Remarks	Temperature Duration Applied current Mounting method Recovery	: 85±2°C : 500+24/-0 hrs : Rated current : Soldering onto PC board : 2 to 3 hrs of recovery under the standard condition after the removal from test chamber.		

13. Bending Strengt	13. Bending Strength		
Specified Value	Appearance : No mechanical damage.		
Test Methods and Remarks	Warp : 2mm Testing board : Glass epoxy-resin substrate Thickness : 0.8mm Board R-230 Harp Warp Harp Harp Harp Harp Harp Harp Harp Harp		



14. Adhesion of Ele	14. Adhesion of Electrode		
Specified Value	No separation or indication of separation of electrode.		
Test Methods and Remarks	Applied force : 5N Duration : 10 sec. Hooked jig Reas Hooked jig Cross-section		

Note on standard condition: "standard condition" referred to herein is defined as follows:

5 to 35°C of temperature, 45 to 85% relative humidity and 86 to 106kPa of air pressure.

When there are questions concerning measurement results:

In order to provide correlation data, the test shall be conducted under condition of $20\pm 2^{\circ}$ C of temperature, 60 to 70% relative humidity and 86 to 106kPa of air pressure. Unless otherwise specified, all the tests are conducted under the "standard condition."

CHIP BEAD INDUCTORS FOR POWER LINE (FB SERIES M TYPE)

PRECAUTIONS

considerations

1. Circuit Design	
Precautions	 Operating environment The products described in this specification are intended for use in general electronic equipment, (office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance. Rated current Rated current of this product is shown in this catalogue, but please be sure to have the base board designed with adequate inspection in case of the generation of heat becomes high within the rated current range when the base board is in high resistance or in bad heating conditions.

2. PCB Design				
Precautions +Land pattern design 1. Please refer to a recommended land pattern.				
3. Considerations for automatic placement				
Precautions	 Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand. 			
Technical	◆Adjustment of mounting machine			

1. When installing products, care should be taken not to apply distortion stress as it may deform the products.

4. Soldering	
Precautions	 Wave soldering Please refer to the specifications in the catalog for a wave soldering. Reflow soldering Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified. Lead free soldering When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to solderin heat, etc. sufficiently. Preheating when soldering The temperature difference between soldering and remaining heat should not be greater than 150°C. Cooling : The temperature difference between the components and cleaning process should not be greater than 100°C. Recommended conditions for using a soldering iron Put the soldering iron on the land-pattern. Soldering iron's temperature – Below 350°C Duration – 3 seconds or less The soldering iron should not directly touch the inductor.
Technical considerations	 Wave, Reflow, Lead free soldering If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequent degrade the reliability of the products. Recommended reflow condition (Pb free solder) Becommended reflow condition (Pb solder) Becommended conditions for using a soldering iron If products are used beyond the range of the recommended conditions heat stresses may deform the products and consequent

1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products.

5. Handling	
Precautions	 Handling Keep the inductors away from all magnets and magnetic objects. Setting PC boards When setting a chip mounted base board, please make sure that there is no residual stress to the chip by distortion in the board or at screw part. Breakaway PC boards (splitting along perforations) When splitting the PC board after mounting inductors, care should be taken not to give any stresses of deflection or twisting to the board.
	 2. Board separation should not be done manually, but by using the appropriate devices. Mechanical considerations 1. Please do not give the inductors any excessive mechanical shocks.
Technical considerations	 ◆Handling 1. There is a case that a characteristic varies with magnetic influence. ◆Setting PC boards
	 There is a case that a characteristic varies with residual stress. ◆Breakaway PC boards (splitting along perforations) Planning pattern configurations and the position of products should be carefully performed to minimize stress.
	 Mechanical considerations 1. There is a case to be damaged by a mechanical shock.

6. Storage conditions	
Precautions	 Storage To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. Recommended conditions
Technical considerations	 Storage Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place.

